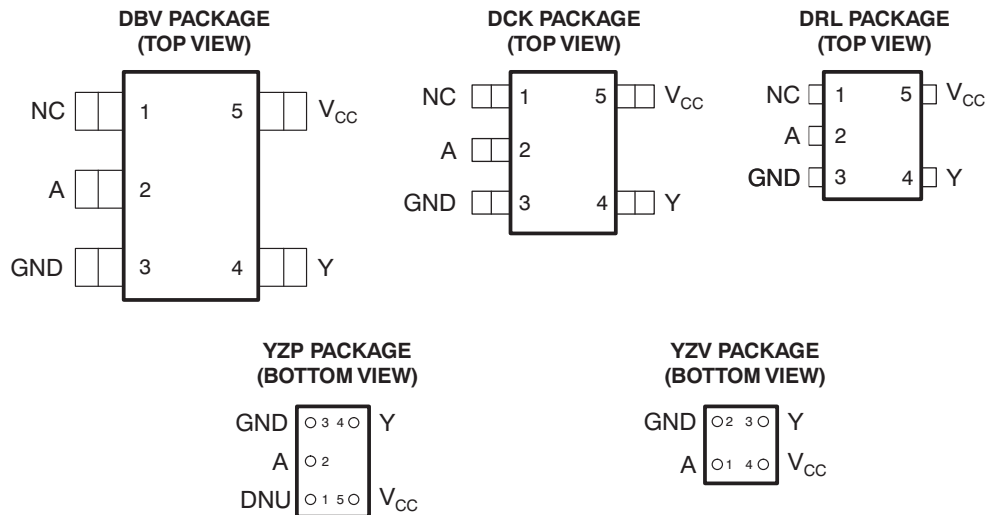


## FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Unbuffered Output
- Max  $t_{pd}$  of 3.7 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 24$ -mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.  
 NC – No internal connection  
 DNU – Do not use

## DESCRIPTION/ORDERING INFORMATION

This single inverter gate is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1GU04 contains one inverter with an unbuffered output and performs the Boolean function  $Y = \bar{A}$ .

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

# SN74LVC1GU04 SINGLE INVERTER GATE

SCES215T – APRIL 1999 – REVISED JANUARY 2007

## ORDERING INFORMATION

| T <sub>A</sub>      | PACKAGE <sup>(1)</sup>  | ORDERABLE PART NUMBER | TOP-SIDE MARKING <sup>(2)</sup> |        |
|---------------------|---|-----------------------|---------------------------------|--------|
| -40°C to 85°C       | NanoFree™ – WCSP (DSBGA)<br>0.23-mm Large Bump – YZP<br>(Pb-free) | Reel of 3000          | SN74LVC1GU04YZPR                | ___CD_ |
|                     | NanoFree™ – WCSP (DSBGA)<br>0.23-mm Large Bump – YZV<br>(Pb-free) |                       | SN74LVC1GU04YZVR                | CD---  |
|                     | SOT (SOT-23) – DBV  | Reel of 3000          | SN74LVC1GU04DBVR                | CU4_   |
|                     |   | Reel of 250           | SN74LVC1GU04DBVT                |        |
|                     | SOT (SC-70) – DCK   | Reel of 3000          | SN74LVC1GU04DCKR                | CD_    |
|                     |   | Reel of 250           | SN74LVC1GU04DCKT                |        |
| SOT (SOT-553) – DRL | Reel of 4000  | SN74LVC1GU04DRLR      | CD_                             |        |

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).
- (2) DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site.  
 YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).  
 YZV: The actual top-side marking is on two lines. Line 1 has four characters to denote year, month, day, and assembly/test site. Line 2 has two characters which show the family and function code. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

## FUNCTION TABLE

| INPUT<br>A | OUTPUT<br>Y |
|------------|-------------|
| H          | L           |
| L          | H           |

## LOGIC DIAGRAM (POSITIVE LOGIC) DBV, DCK, DRL, and YZP PACKAGE



## YZV PACKAGE



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

|                  |  | RATING                        | UNIT |
|------------------|--|-------------------------------|------|
| V <sub>CC</sub>  | Supply voltage range   | –0.5 to 6.5                   | V    |
| V <sub>I</sub>   | Input voltage range <sup>(2)</sup>   | 0.5 to 6.5                    | V    |
| V <sub>O</sub>   | Voltage range applied to any output in the high or low state <sup>(2)(3)</sup> | –0.5 to V <sub>CC</sub> + 0.5 | V    |
| I <sub>IK</sub>  | Input clamp current  | V <sub>I</sub> < 0            | –50  |
| I <sub>OK</sub>  | Output clamp current   | V <sub>O</sub> < 0            | –50  |
| I <sub>O</sub>   | Continuous output current  | ±50                           | mA   |
|                  | Continuous current through V <sub>CC</sub> or GND                              | ±100                          | mA   |
| θ <sub>JA</sub>  | Package thermal impedance <sup>(4)</sup>                                       | DBV package                   | 206  |
|                  |  | DCK package                   | 252  |
|                  |  | DRL package                   | 142  |
|                  |  | YZP package                   | 132  |
|                  |  | YZV package                   | 116  |
| T <sub>stg</sub> | Storage temperature range  | –65 to 150                    | °C   |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)</sup>

|                 |                                | MIN                      | MAX                    | UNIT |
|-----------------|--------------------------------|--------------------------|------------------------|------|
| V <sub>CC</sub> | Supply voltage                 | 1.65                     | 5.5                    | V    |
| V <sub>IH</sub> | High-level input voltage       | I <sub>O</sub> = –100 μA | 0.75 × V <sub>CC</sub> | V    |
| V <sub>IL</sub> | Low-level input voltage        | I <sub>O</sub> = 100 μA  | 0.25 × V <sub>CC</sub> | V    |
| V <sub>I</sub>  | Input voltage                  | 0                        | 5.5                    | V    |
| V <sub>O</sub>  | Output voltage                 | 0                        | V <sub>CC</sub>        | V    |
| I <sub>OH</sub> | High-level output current      | V <sub>CC</sub> = 1.65 V | –4                     | mA   |
|                 |                                | V <sub>CC</sub> = 2.3 V  | –8                     |      |
|                 |                                | V <sub>CC</sub> = 3 V    | –16                    |      |
|                 |                                |                          | –24                    |      |
|                 |                                | V <sub>CC</sub> = 4.5 V  | –32                    |      |
| I <sub>OL</sub> | Low-level output current       | V <sub>CC</sub> = 1.65 V | 4                      | mA   |
|                 |                                | V <sub>CC</sub> = 2.3 V  | 8                      |      |
|                 |                                | V <sub>CC</sub> = 3 V    | 16                     |      |
|                 |                                |                          | 24                     |      |
|                 |                                | V <sub>CC</sub> = 4.5 V  | 32                     |      |
| T <sub>A</sub>  | Operating free-air temperature | –40                      | 85                     | °C   |

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74LVC1GU04 SINGLE INVERTER GATE

SCES215T – APRIL 1999 – REVISED JANUARY 2007

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER       | TEST CONDITIONS                   |   | V <sub>CC</sub> | MIN                   | TYP <sup>(1)</sup> | MAX  | UNIT |
|-----------------|-----------------------------------|---|-----------------|-----------------------|--------------------|------|------|
| V <sub>OH</sub> | V <sub>IL</sub> = 0 V             | I <sub>OH</sub> = -100 μA                         | 1.65 V to 5.5 V | V <sub>CC</sub> - 0.1 |                    |      | V    |
|                 |                                   | I <sub>OH</sub> = -4 mA                           | 1.65 V          | 1.2                   |                    |      |      |
|                 |                                   | I <sub>OH</sub> = -8 mA                           | 2.3 V           | 1.9                   |                    |      |      |
|                 |                                   | I <sub>OH</sub> = -16 mA                          | 3 V             | 2.4                   |                    |      |      |
|                 |                                   | I <sub>OH</sub> = -24 mA                          |                 | 2.3                   |                    |      |      |
|                 |                                   | I <sub>OH</sub> = -32 mA                          | 4.5 V           | 3.8                   |                    |      |      |
| V <sub>OL</sub> | V <sub>IH</sub> = V <sub>CC</sub> | I <sub>OL</sub> = 100 μA                          | 1.65 V to 5.5 V |                       |                    | 0.1  | V    |
|                 |                                   | I <sub>OL</sub> = 4 mA                            | 1.65 V          |                       |                    | 0.45 |      |
|                 |                                   | I <sub>OL</sub> = 8 mA                            | 2.3 V           |                       |                    | 0.3  |      |
|                 |                                   | I <sub>OL</sub> = 16 mA                           | 3 V             |                       |                    | 0.4  |      |
|                 |                                   | I <sub>OL</sub> = 24 mA                           |                 |                       |                    | 0.55 |      |
|                 |                                   | I <sub>OL</sub> = 32 mA                           | 4.5 V           |                       |                    | 0.55 |      |
| I <sub>I</sub>  | A input                           | V <sub>I</sub> = 5.5 V or GND                     | 0 to 5.5 V      |                       |                    | ±5   | μA   |
| I <sub>CC</sub> |                                   | V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0 | 1.65 V to 5.5 V |                       |                    | 10   | μA   |
| C <sub>i</sub>  |                                   | V <sub>I</sub> = V <sub>CC</sub> or GND           | 3.3 V           |                       | 7                  |      | pF   |

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (See [Figure 1](#))

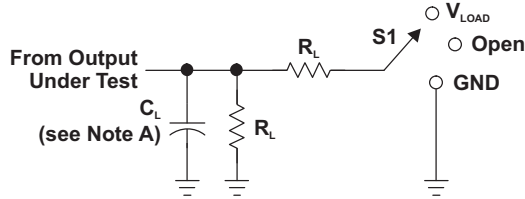
| PARAMETER       | FROM (INPUT) | TO (INPUT) | V <sub>CC</sub> = 1.8 V ± 0.15 V |     | V <sub>CC</sub> = 2.5 V ± 0.2 V |     | V <sub>CC</sub> = 3.3 V ± 0.3 V |     | V <sub>CC</sub> = 5 V ± 0.5 V |     | UNIT |
|-----------------|--------------|------------|----------------------------------|-----|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
|                 |              |            | MIN                              | MAX | MIN                             | MAX | MIN                             | MAX | MIN                           | MAX |      |
| t <sub>pd</sub> | A            | Y          | 1.3                              | 5   | 1                               | 4   | 1.1                             | 3.7 | 1                             | 3   | ns   |

## Operating Characteristics

T<sub>A</sub> = 25°C

| PARAMETER       | TEST CONDITIONS               | V <sub>CC</sub> = 1.8 V | V <sub>CC</sub> = 2.5 V | V <sub>CC</sub> = 3.3 V | V <sub>CC</sub> = 5 V | UNIT |    |
|-----------------|-------------------------------|-------------------------|-------------------------|-------------------------|-----------------------|------|----|
|                 |                               | TYP                     | TYP                     | TYP                     | TYP                   |      |    |
| C <sub>pd</sub> | Power dissipation capacitance | f = 10 MHz              | 9                       | 11                      | 13                    | 27   | pF |

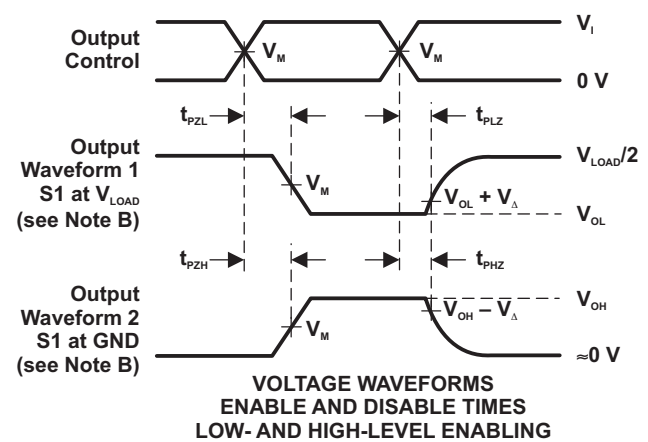
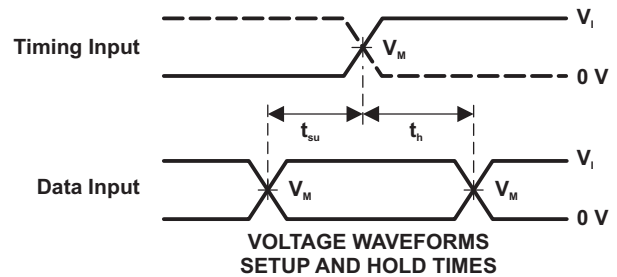
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

| TEST              | S1         |
|-------------------|------------|
| $t_{PLH}/t_{PHL}$ | Open       |
| $t_{PLZ}/t_{PZL}$ | $V_{LOAD}$ |
| $t_{PHZ}/t_{PZH}$ | GND        |

| $V_{CC}$                         | INPUTS   |                      | $V_M$      | $V_{LOAD}$        | $C_L$ | $R_L$        | $V_{\Delta}$ |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
|                                  | $V_I$    | $t/t_i$              |            |                   |       |              |              |
| $1.8\text{ V} \pm 0.15\text{ V}$ | $V_{CC}$ | $\leq 2\text{ ns}$   | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k $\Omega$ | 0.15 V       |
| $2.5\text{ V} \pm 0.2\text{ V}$  | $V_{CC}$ | $\leq 2\text{ ns}$   | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 $\Omega$ | 0.15 V       |
| $3.3\text{ V} \pm 0.3\text{ V}$  | 3 V      | $\leq 2.5\text{ ns}$ | 1.5 V      | 6 V               | 50 pF | 500 $\Omega$ | 0.3 V        |
| $5\text{ V} \pm 0.5\text{ V}$    | $V_{CC}$ | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 $\Omega$ | 0.3 V        |



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_o = 50\ \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 74LVC1GU04DBVRE4 | ACTIVE                | SOT-23       | DBV             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DBVRG4 | ACTIVE                | SOT-23       | DBV             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DBVTE4 | ACTIVE                | SOT-23       | DBV             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DBVTG4 | ACTIVE                | SOT-23       | DBV             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DCKRE4 | ACTIVE                | SC70         | DCK             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DCKRG4 | ACTIVE                | SC70         | DCK             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DCKTE4 | ACTIVE                | SC70         | DCK             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DCKTG4 | ACTIVE                | SC70         | DCK             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| 74LVC1GU04DRLRG4 | ACTIVE                | SOT          | DRL             | 5    | 4000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04DBVR | ACTIVE                | SOT-23       | DBV             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04DBVT | ACTIVE                | SOT-23       | DBV             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04DCKR | ACTIVE                | SC70         | DCK             | 5    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04DCKT | ACTIVE                | SC70         | DCK             | 5    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04DRLR | ACTIVE                | SOT          | DRL             | 5    | 4000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LVC1GU04YZPR | ACTIVE                | DSBGA        | YZP             | 5    | 3000        | TBD                     | Call TI          | Call TI                      |
| SN74LVC1GU04YZVR | ACTIVE                | DSBGA        | YZV             | 4    | 3000        | TBD                     | Call TI          | Call TI                      |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

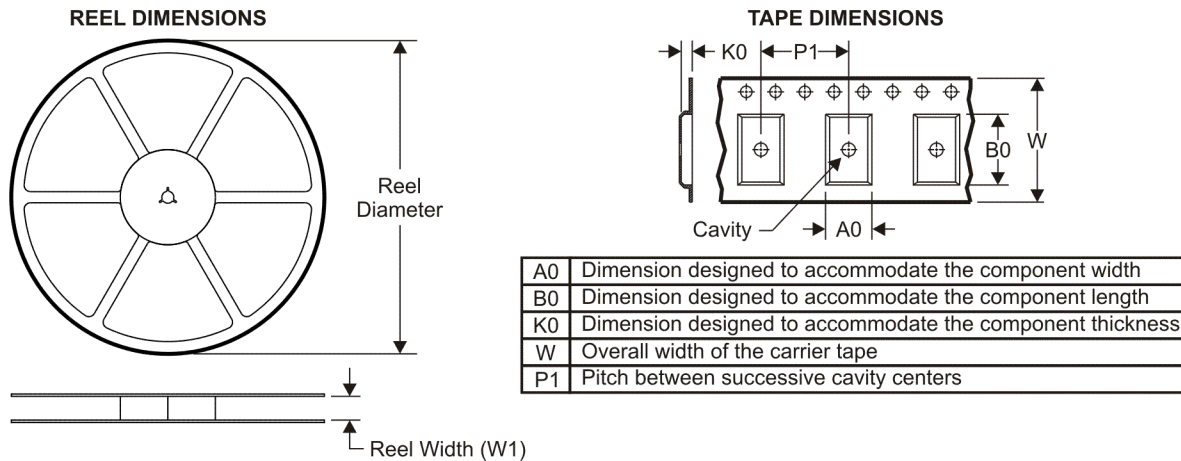
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1GU04DBVR | SOT-23       | DBV             | 5    | 3000 | 180.0              | 9.2                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DBVR | SOT-23       | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DBVT | SOT-23       | DBV             | 5    | 250  | 180.0              | 9.2                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DCKR | SC70         | DCK             | 5    | 3000 | 180.0              | 9.2                | 2.24    | 2.34    | 1.22    | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DCKR | SC70         | DCK             | 5    | 3000 | 178.0              | 9.0                | 2.4     | 2.5     | 1.2     | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DCKT | SC70         | DCK             | 5    | 250  | 180.0              | 9.2                | 2.24    | 2.34    | 1.22    | 4.0     | 8.0    | Q3            |
| SN74LVC1GU04DRLR | SOT          | DRL             | 5    | 4000 | 180.0              | 9.2                | 1.78    | 1.78    | 0.69    | 4.0     | 8.0    | Q3            |



**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1GU04DBVR | SOT-23       | DBV             | 5    | 3000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1GU04DBVR | SOT-23       | DBV             | 5    | 3000 | 565.0       | 140.0      | 75.0        |
| SN74LVC1GU04DBVT | SOT-23       | DBV             | 5    | 250  | 202.0       | 201.0      | 28.0        |
| SN74LVC1GU04DCKR | SC70         | DCK             | 5    | 3000 | 205.0       | 200.0      | 33.0        |
| SN74LVC1GU04DCKR | SC70         | DCK             | 5    | 3000 | 565.0       | 140.0      | 75.0        |
| SN74LVC1GU04DCKT | SC70         | DCK             | 5    | 250  | 205.0       | 200.0      | 33.0        |
| SN74LVC1GU04DRLR | SOT          | DRL             | 5    | 4000 | 202.0       | 201.0      | 28.0        |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

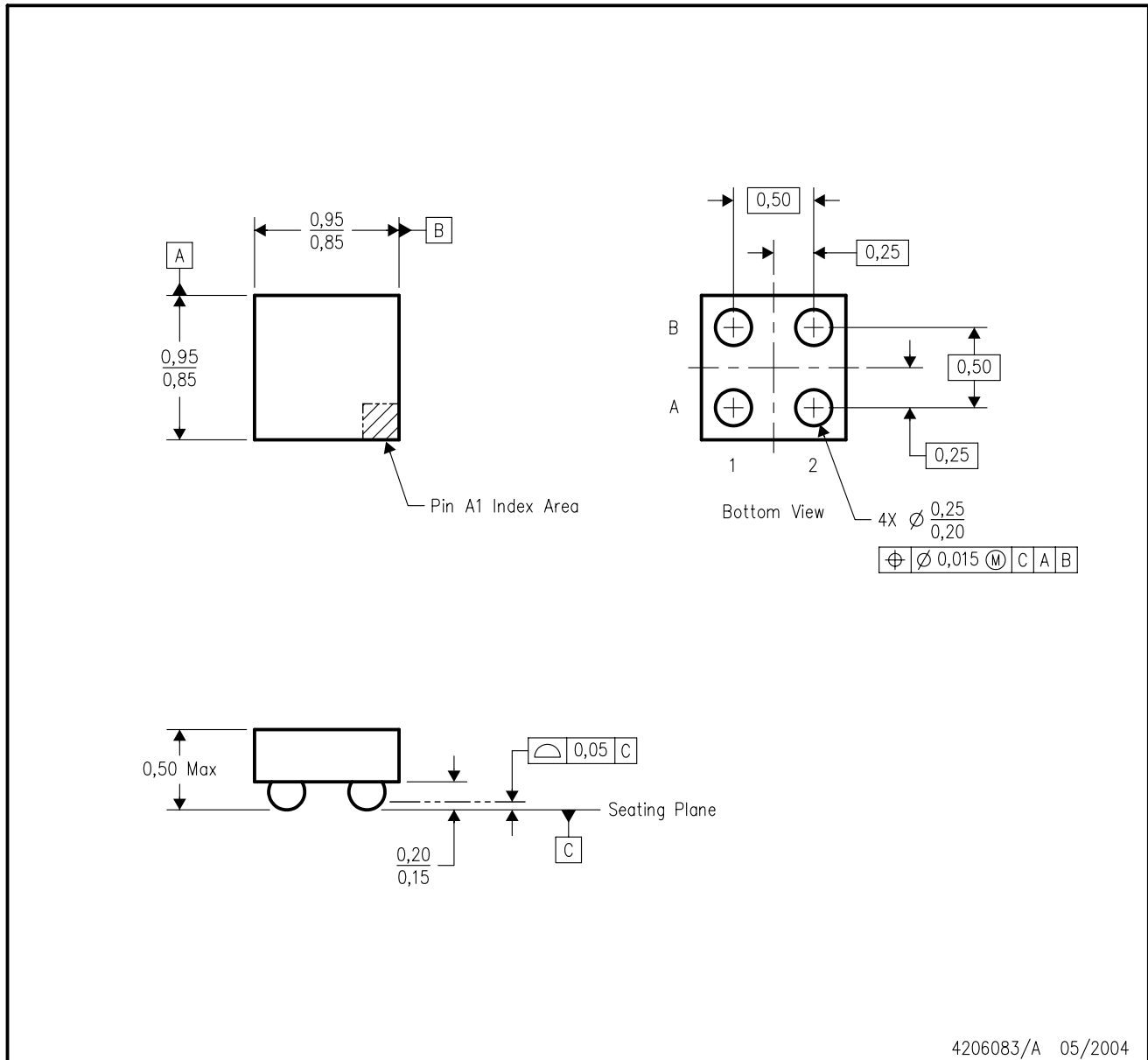
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.

YZV (S-XBGA-N4)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package contains lead-free balls. Refer to the 4 YEV package (drawing 4206082) for tin-lead (SnPb) balls.

NanoFree is a trademark of Texas Instruments.

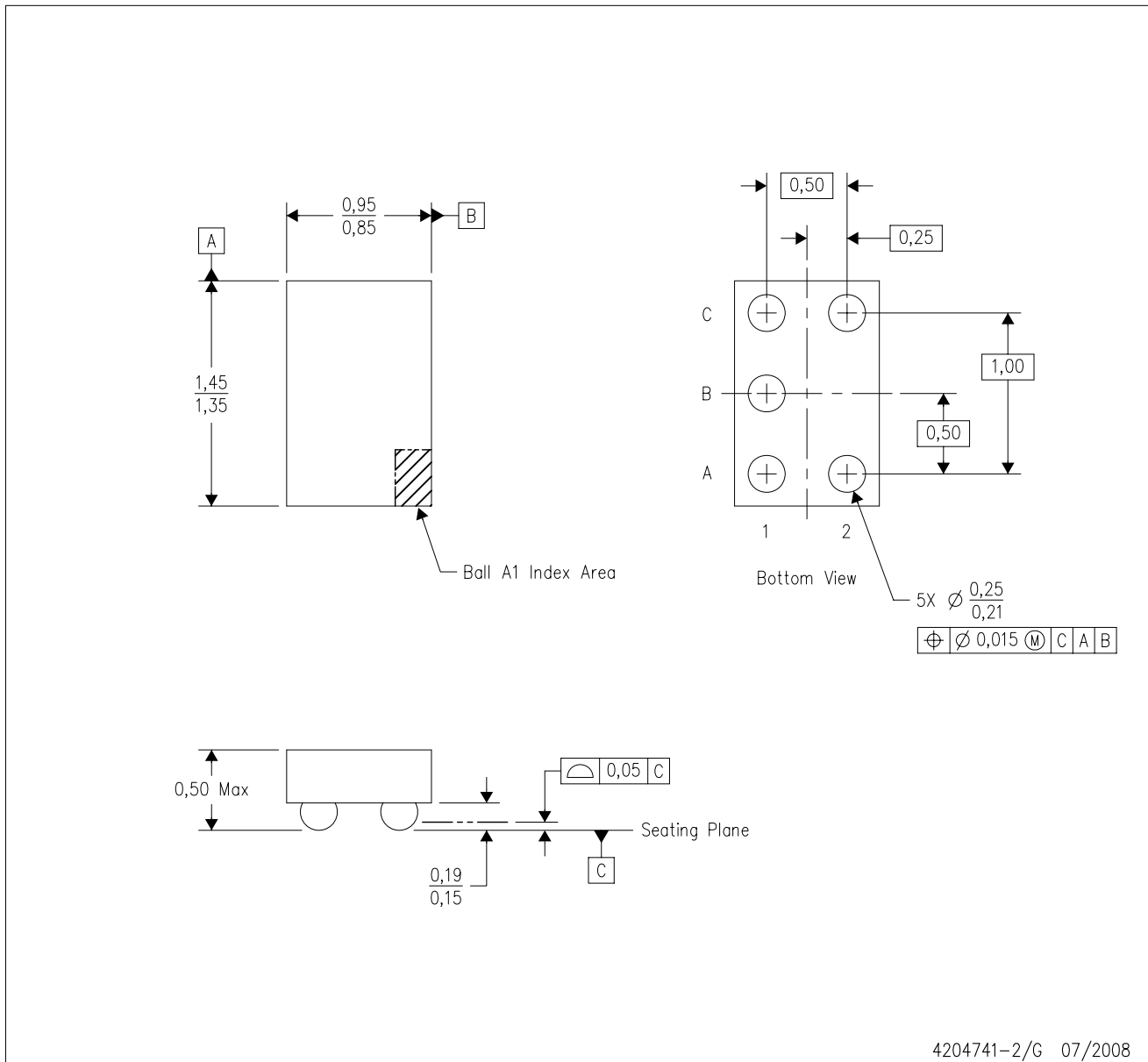


4205622-2/D 08/2007

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
  - D. JEDEC package registration is pending.

YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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